

Final Product Change Notification

201706004F01

Issue Date: 14-Jul-2017
Effective Date: 12-Oct-2017

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 For detailed information we invite you to view this notification online



Management Summary

- Replace Au (gold) wire with Cu (copper) wire in bonding process
- Expansion of second source ASEN assembly

Change Category

- | | | | | |
|----------------------------------------------|--------------------------------------------------------|----------------------------------------------------|-----------------------------------------|---------------------------------------------------------|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Release of Cu-wire bonding for the DHVQFN packages in ASEN and ATBK

Details of this Change

Release of Cu-wire bonding for the DHVQFN packages in ASEN and ATBK (phase 7)

- Release Cu (copper) wire in bonding process
- Assembly locations: ASEN (NXP-ASE JV Suzhou, China) and ATBK (NXP Semiconductors Assembly & Test Plant Bangkok, Thailand)
- No change in datasheet, form, fit, function, quality or reliability anticipated
- No change in ordering code 12NC's and product type number

Remark: DHVQFN20 types assembled in ATBK were already released with Cu-wire bonding since 2015 and therefore only ASEN capacity expansion is applicable for this PCN

Why do we Implement this Change

- Next phase in Cu wire release after maturation in commodity Logic products since 2012

- Continued alignment with world technology trends on state of the art production tools
- Copper wire shows enhanced mechanical properties
- Increased environmental friendliness (eco-friendly)
- Capacity expansion in ASEN

Identification of Affected Products

- Assembly changes can be identified by backward traceability of the product marking date code
- Applied assembly location (ASEN or ATBK) is indicated on the reel and box label

Product Availability

Sample Information

Samples are available upon request

Samples are available upon request from the Logic sample store Nijmegen The Netherlands

Production

Planned first shipment 12-Oct-2017

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification Issue Date Effective Date Title

Notification	Issue Date	Effective Date	Title
201409013F0109	Jan-2015	24-Apr-2015	Introduction of Cu-wire bonding for TSSOP5 and DHVQFN20 packages (Phase IV)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 13-Aug-2017.

Remarks

Assembly location indicator suffix on reel label and product topside marking:

"X"= ASEN (NXP-ASE JV Suzhou, China)

"n"= ATBK (NXP Semiconductors Assembly & Test Plant Bangkok, Thailand)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Logic Customer Support
e-mail address logic.helpdesk@nexperia.com

At Nexperia B.V we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

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Affected Part Numbers

74LVC244ABQ,115	74LVC574ABQ,115	74HCT00BQ,115	74LVC132ABQ,115
74VHCT245BQ,115	74LVC574ABQ,115	74LVC541ABQ,115	74AHC123ABQ,115
74LVC07ABQ,115	74LVC245ABQ,115	74LVC541ABQ,115	74AHC123ABQ,115
74LVC138ABQ,115	74LVC32ABQ,115	74HCT4051BQ,115	74AHC08BQ,115
74LVC138ABQ,115	74LVC32ABQ,115	74HCT4051BQ,115	74AHC08BQ,115
74LVC14ABQ,115	74HC74BQ,115	74HC245BQ,115	74HC165BQ,115
74LVC14ABQ,115	74LVC04ABQ,115	74HC245BQ,115	74HC165BQ,115
74LVC573ABQ,115	74HC4051BQ,115	74AHC595BQ,115	74LVC244ABQ,115
74LVC573ABQ,115	74HC4051BQ,115	74AHC595BQ,115	